MC74HC160A

Presettable Counters

High−Performance Silicon−Gate CMOS

The MC74HC160A is identical in pinout to the LS160. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The HC160A is a programmable BCD counters with asynchronous Reset input.

Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 234 FETs or 58.5 Equivalent Gates
- These are Pb−Free Devices

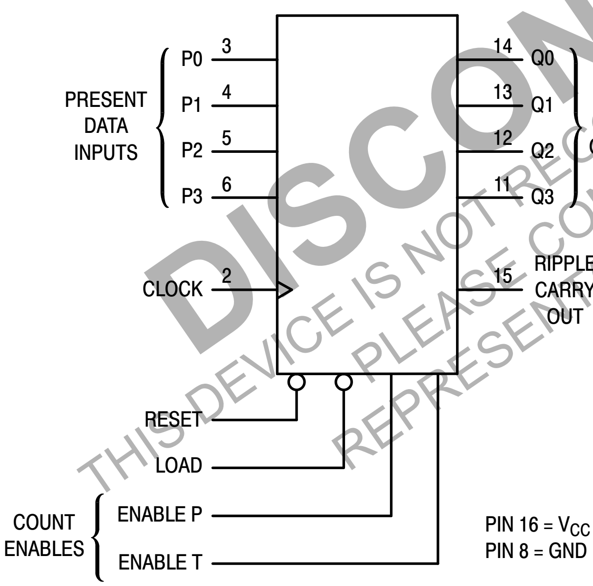

Figure 1. Logic Diagram

Device	Count Mode	Reset Mode
HC160	BCD	Asynchronous

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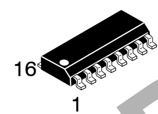
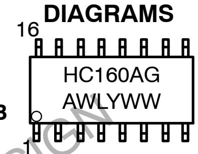
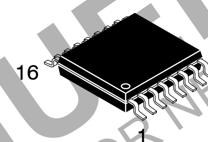
MARKING DIAGRAMS

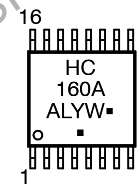


SOIC−16
D SUFFIX
CASE 751B



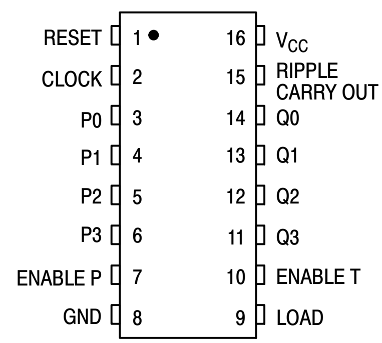


TSSOP−16
DT SUFFIX
CASE 948F



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or ▪ = Pb−Free Package
(Note: Microdot may be in either location)

PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

FUNCTION TABLE

Inputs					Outputs
Clock	**Reset***	**Load**	**Enable P**	**Enable T**	**Q**
↑	L	X	X	X	Reset
↑	H	L	X	X	Load Preset Data
↑	H	H	H	H	Count
↑	H	H	L	X	No Count
↑	H	H	X	L	No Count

*HC160 is an Asynchronous Reset Device.
H = High Level
L = Low Level
X = Don't Care

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} + 0.5	V
V_{out}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} + 0.5	V
I_{in}	DC Input Current, per Pin	±20	mA
I_{out}	DC Output Current, per Pin	±25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	±50	mA
P_D	Power Dissipation in Still Air, Plastic or Ceramic DIP† SOIC Package†	750 500	mW
T_{stg}	Storage Temperature	–65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
†Derating – SOIC Package: – 7 mW/°C from 65° to 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high−impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V
T_A	Operating Temperature, All Package Types	–55	+125	°C
t_r, t_f	Input Rise and Fall Time (Figure 3) V_{CC} = 2.0 V V_{CC} = 4.5 V V_{CC} = 6.0 V	0 0 0	1000 500 400	ns

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V_{CC} V	Guaranteed Limit – 55 to 25°C	≤ 85°C	≤ 125°C	Unit
V_{IH}	Minimum High−Level Input Voltage	V_{out} = 0.1 V or V_{CC} − 0.1 V $\lvert I_{out}\rvert \le 20\ \mu A$	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
V_{IL}	Maximum Low−Level Input Voltage	V_{out} = 0.1 V or V_{CC} − 0.1 V $\lvert I_{out}\rvert \le 20\ \mu A$	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V
V_{OH}	Minimum High−Level Output Voltage	$V_{in} = V_{IH}$ or V_{IL} $\lvert I_{out}\rvert \le 20\ \mu A$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{in} = V_{IH}$ or V_{IL} $\lvert I_{out}\rvert \le 2.4$ m $\lvert I_{out}\rvert \le 4.0$ mA $\lvert I_{out}\rvert \le 5.2$ mA	3.0 4.5 6.0	2.48 3.98 5.48	2.34 3.84 5.34	2.20 3.70 5.20	
V_{OL}	Maximum Low−Level Output Voltage	$V_{in} = V_{IH}$ or V_{IL} $\lvert I_{out}\rvert \le 20\ \mu A$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{in} = V_{IH}$ or V_{IL} $\lvert I_{out}\rvert \le 2.4$ m $\lvert I_{out}\rvert \le 4.0$ mA $\lvert I_{out}\rvert \le 5.2$ mA	3.0 4.5 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.40 0.40 0.40	
I_{in}	Maximum Input Leakage Current	$V_{in} = V_{CC}$ or GND	6.0	± 0.1	± 1.0	± 1.0	μA
I_{CC}	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0\ \mu A$	6.0	4	40	160	μA

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6 ns)

Symbol	Parameter	V_{CC} V	Guaranteed Limit – 55 to 25°C	≤ 85°C	≤ 125°C	Unit
f_{max}	Maximum Clock Frequency (50% Duty Cycle)* (Figures 3 and 8)	2.0 4.5 6.0	6.0 30 35	4.8 24 28	4.0 20 24	MHz
t_{PLH}	Maximum Propagation Delay, Clock to Q (Figures 3 and 8)	2.0 4.5 6.0	170 34 29	215 43 37	255 51 43	ns
t_{PHL}		2.0 4.5 6.0	205 41 35	255 51 43	310 62 53	
t_{PHL}	Maximum Propagation Delay, Reset to Q (HC160A Only) (Figures 4 and 8)	2.0 4.5 6.0	210 42 36	265 53 45	315 63 54	ns
t_{PLH}	Maximum Propagation Delay, Enable T to Ripple Carry Out (Figures 5 and 8)	2.0 4.5 6.0	160 32 27	200 40 34	240 48 41	ns
t_{PHL}		2.0 4.5 6.0	195 39 33	245 49 42	295 59 50	
t_{PLH}	Maximum Propagation Delay, Clock to Ripple Carry Out (Figures 3 and 8)	2.0 4.5 6.0	175 35 30	220 44 37	265 53 45	ns
t_{PHL}		2.0 4.5 6.0	215 43 37	270 54 46	325 65 55	
t_{PHL}	Maximum Propagation Delay, Reset to Ripple Carry Out (HC160A Only) (Figures 4 and 8)	2.0 4.5 6.0	220 44 37	275 55 47	330 66 56	ns
t_{TLH}, t_{THL}	Maximum Output Transition Time, Any Output (Figures 3 and 8)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C_{in}	Maximum Input Capacitance	–	10	10	10	pF

*Applies to noncascaded/nonsynchronously clocked configurations only. With synchronously cascaded counters, (1) Clock to Ripple Carry Out propagation delays, (2) Enable T or Enable P to Clock setup times, and (3) Clock to Enable T or Enable P hold times determine f_{max}. However, if Ripple Carry Out of each stage is tied to the Clock of the next stage (nonsynchronously clocked), the f_{max} in the table above is applicable. See Applications Information in this data sheet.

		Typical @ 25°C, V_{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Per Package)*	60	pF

*Used to determine the no−load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.

TIMING REQUIREMENTS (Input t_r = t_f = 6 ns)

Symbol	Parameter	V_{CC} V	Guaranteed Limit – 55 to 25°C	≤ 85°C	≤ 125°C	Unit
t_{su}	Minimum Setup Time, Preset Data Inputs to Clock (Figure 6)	2.0 4.5 6.0	150 30 26	190 38 33	225 45 38	ns
t_{su}	Minimum Setup Time, Load to Clock (Figure 6)	2.0 4.5 6.0	135 27 23	170 34 29	205 41 35	ns
t_{su}	Minimum Setup Time, Enable T or Enable P to Clock (Figure 7)	2.0 4.5 6.0	200 40 34	250 50 43	300 60 51	ns
t_h	Minimum Hold Time, Clock to Preset Data Inputs (Figure 6)	2.0 4.5 6.0	50 10 9	65 13 11	75 15 13	ns
t_h	Minimum Hold Time, Clock to Load (Figure 6)	2.0 4.5 6.0	3 3 3	3 3 3	3 3 3	ns
t_h	Minimum Hold Time, Clock to Enable T or Enable P (Figure 7)	2.0 4.5 6.0	3 3 3	3 3 3	3 3 3	ns
t_{rec}	Minimum Recovery Time, Reset Inactive to Clock (Figure 4)	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
t_{rec}	Minimum Recovery Time, Load Inactive to Clock (Figure 6)	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
t_w	Minimum Pulse Width, Clock (Figure 3)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
t_w	Minimum Pulse Width, Reset (Figure 4)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
t_r, t_f	Maximum Input Rise and Fall Times (Figure 3)	2.0 4.5 6.0	1000 500 400	1000 500 400	1000 500 400	ns

FUNCTION DESCRIPTION

The HC160A is a programmable 4−bit synchronous counters that feature parallel Load, synchronous or asynchronous Reset, a Carry Output for cascading, and count−enable controls. The HC160A is a BCD counter with asynchronous Reset.

INPUTS

Clock (Pin 2)

The internal flip−flops toggle and the output count advances with the rising edge of the Clock input. In addition, control functions, such as loading occur with the rising edge of the Clock input.

Preset Data Inputs P0, P1, P2, P3 (Pins 3, 4, 5, 6)

These are the data inputs for programmable counting. Data on these pins may be synchronously loaded into the internal flip−flops and appear at the counter outputs. P0 (pin 3) is the least−significant bit and P3 (pin 6) is the most−significant bit.

OUTPUTS

Q0, Q1, Q2, Q3 (Pins 14, 13, 12, 11)

These are the counter outputs (BCD or binary). Q0 (pin 14) is the least−significant bit and Q3 (pin 11) is the most−significant bit.

Ripple Carry Out (Pin 15)

When the counter is in its maximum state (1001 for the BCD counters or 1111 for the binary counters), this output goes high, providing an external look−ahead carry pulse that may be used to enable successive cascaded counters. Ripple Carry Out remains high only during the maximum count state. The logic equation for this output is:

Ripple Carry Out = Enable T • Q0 • $\overline{Q1}$ • $\overline{Q2}$ • Q3 for BCD counters

CONTROL FUNCTIONS

Resetting

A low level on the Reset pin (pin 1) resets the internal flip−flops and sets the outputs (Q0 through Q3) to a low level. The HC160A resets asynchronously.

Loading

With the rising edge of the Clock, a low level on Load (pin 9) loads the data from the Preset Data Input pins (P0, P1, P2, P3) into the internal flip−flops and onto the output pins, Q0 through Q3. The count function is disabled as long as Load is low.

Although the HC160A is a BCD counters, they may be programmed to any state. If they are loaded with a state disallowed in BCD code, they will return to their normal count sequence within two clock pulses (see the Output State Diagram).

Count Enable/Disable

These devices have two count−enable control pins: Enable P (pin 7) and Enable T (pin 10). The devices count when these two pins and the Load pin are high. The logic equation is:

Count Enable = Enable P • Enable T • Load

The count is either enabled or disabled by the control inputs according to Table 1. In general, Enable P is a count−enable control; Enable T is both a count−enable and a Ripple−Carry Output control.

Table 1. COUNT ENABLE/DISABLE

Control Inputs			Result at Outputs	
Load	Enable P	Enable T	Q0 – Q3	Ripple Carry Out
H	H	H	Count	High when Q0 – Q3 are maximum*
L	H	H	No Count	
X	L	H	No Count	High when Q0 – Q3 are maximum*
X	X	L	No Count	L

*Q0 through Q3 are maximum for the HC160A when Q3 Q2 Q1 Q0 = 1001.

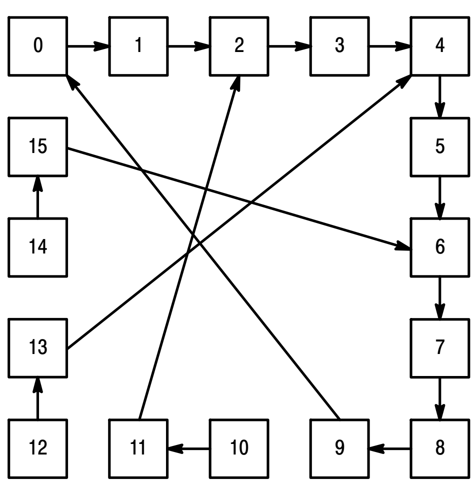


Figure 2. Output State Diagrams HC160A BCD Counters

SWITCHING WAVEFORMS

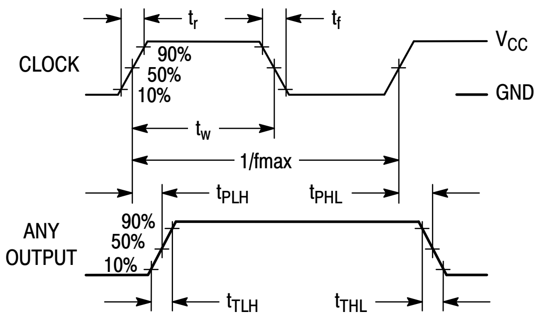


Figure 3.

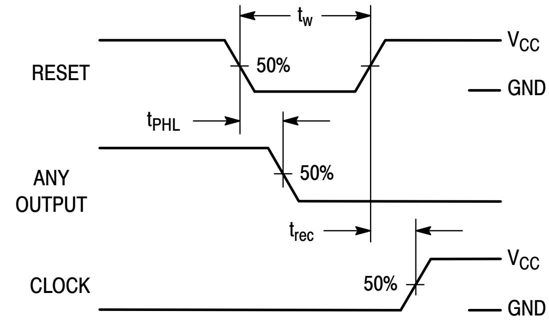


Figure 4.

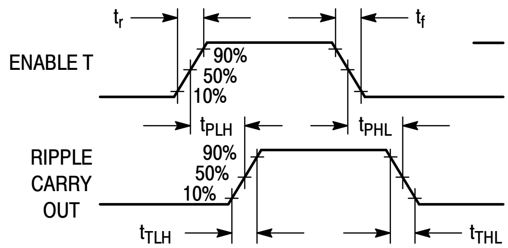


Figure 5.

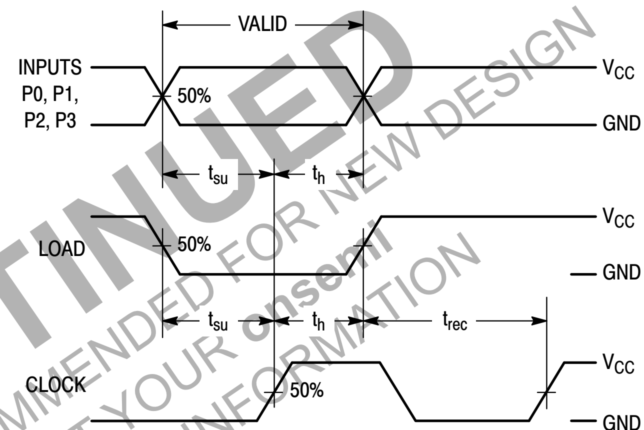


Figure 6.

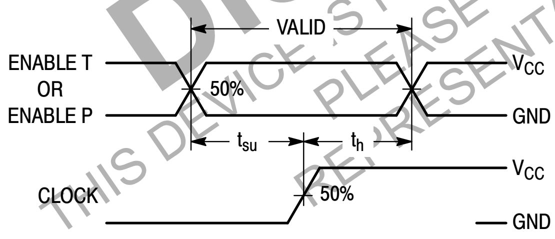
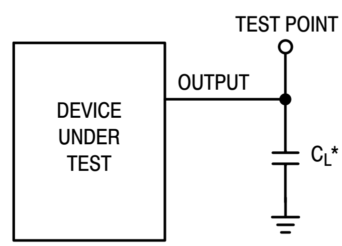


Figure 7.

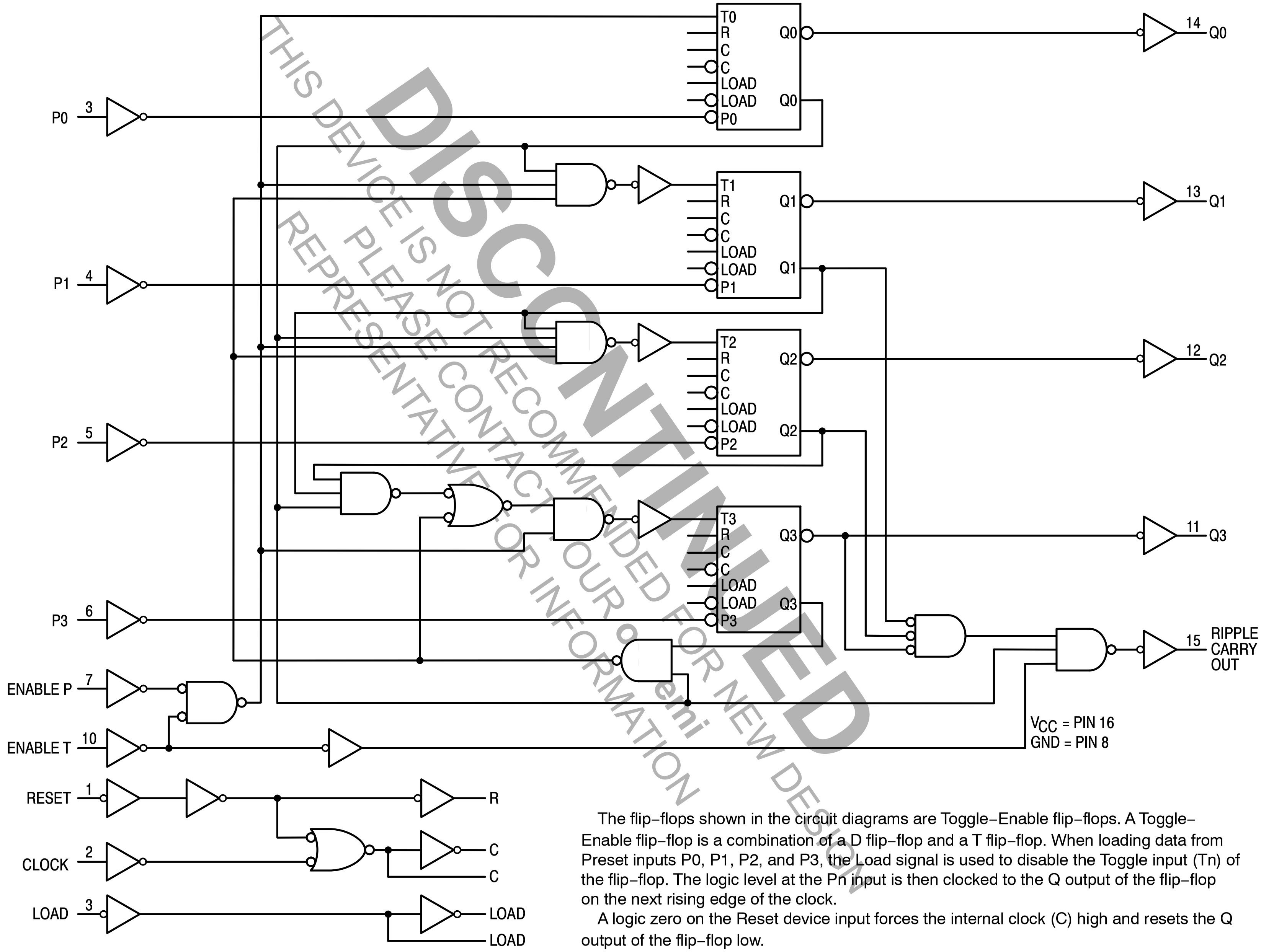
TEST CIRCUIT



*Includes all probe and jig capacitance

Figure 8.

MC74HC160A
BCD Counter with Asynchronous Reset



The flip-flops shown in the circuit diagrams are Toggle-Enable flip-flops. A Toggle-Enable flip-flop is a combination of a D flip-flop and a T flip-flop. When loading data from Preset inputs P0, P1, P2, and P3, the Load signal is used to disable the Toggle input (Tn) of the flip-flop. The logic level at the Pn input is then clocked to the Q output of the flip-flop on the next rising edge of the clock.

A logic zero on the Reset device input forces the internal clock (C) high and resets the Q output of the flip-flop low.

Sequence illustrated in waveforms:
1. Reset outputs to zero.
2. Preset to BCD seven.
3. Count to eight, nine, zero, one, two, and three.
4. Inhibit.

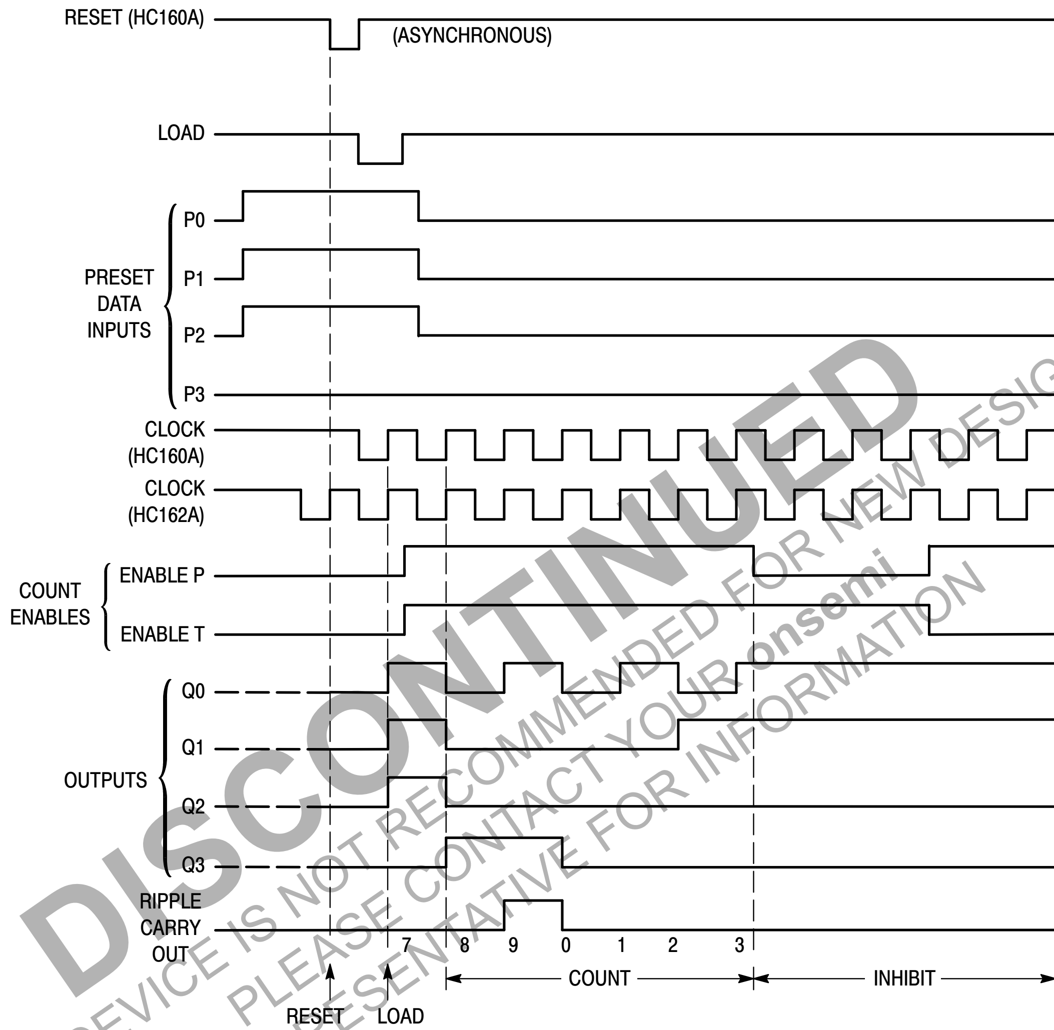
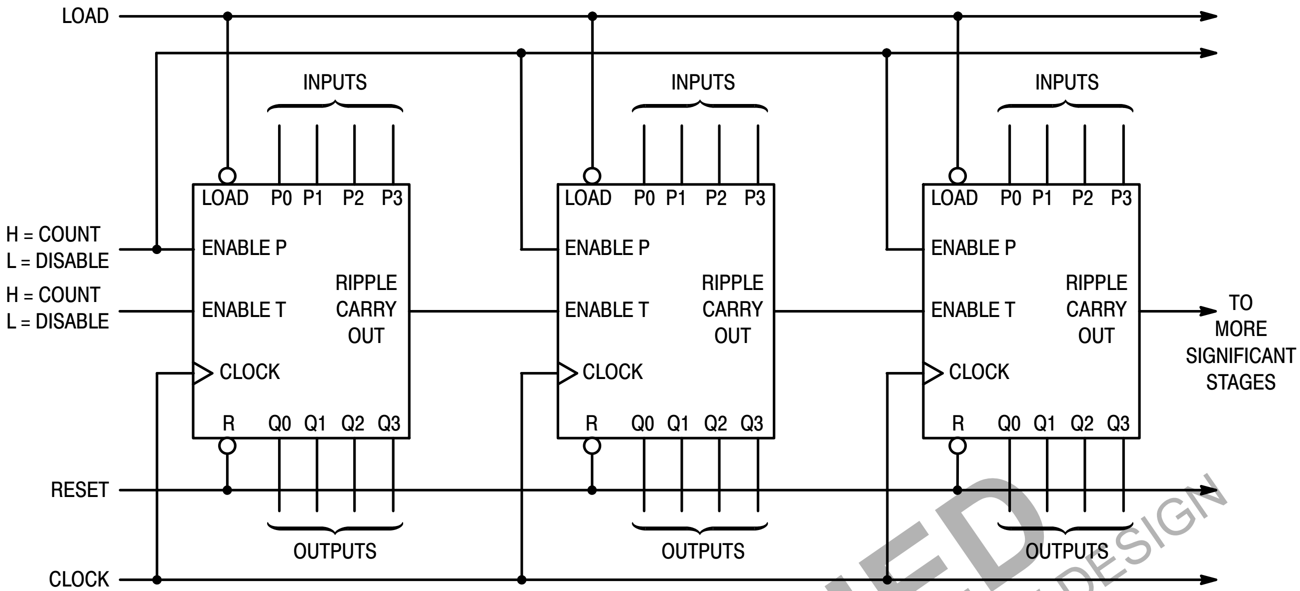


Figure 9. MC74HC160A Timing Diagram

TYPICAL APPLICATIONS CASCADING



NOTE: When used in these cascaded configurations the clock f_{max} guaranteed limits may not apply. Actual performance will depend on number of stages. This limitation is due to set up times between Enable (Port) and Clock.

Figure 10. N−Bit Synchronous Counters

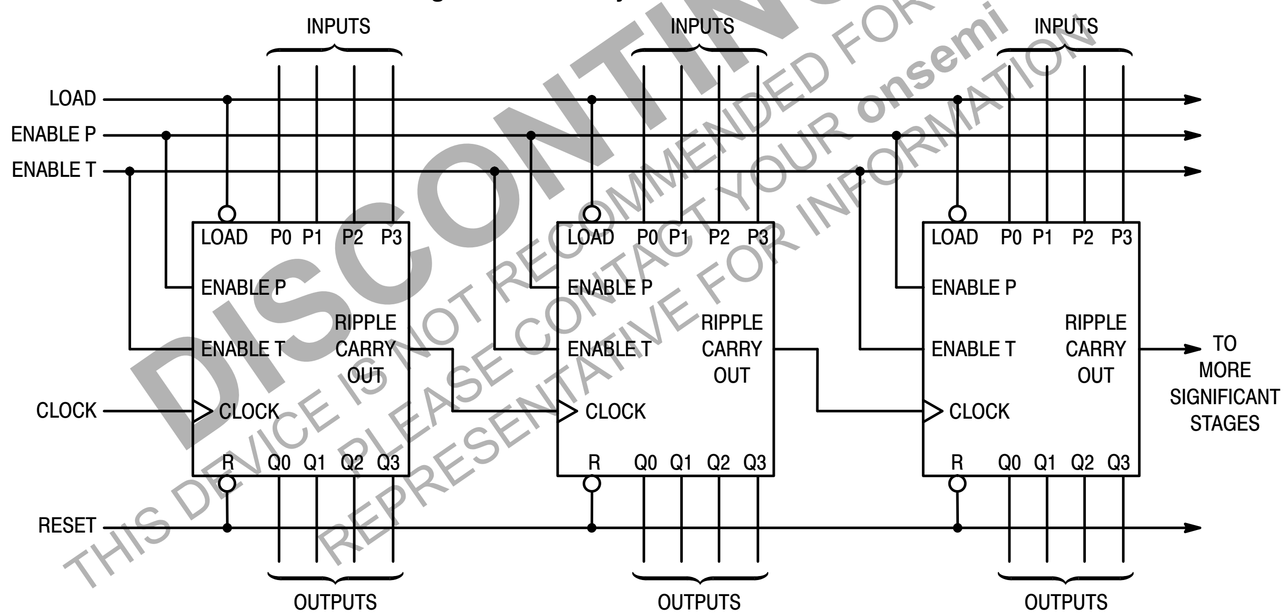
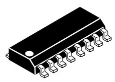


Figure 11. Nibble Ripple Counter

ORDERING INFORMATION

Device	Package	Shipping†
MC74HC160ADG	SOIC−16 (Pb−Free)	48 Units / Rail
MC74HC160ADR2G	SOIC−16 (Pb−Free)	2500 Tape & Reel
MC74HC160ADTG	TSSOP−16*	96 Units / Rail
MC74HC160ADTR2G	TSSOP−16*	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb−Free.



SCALE 1:1

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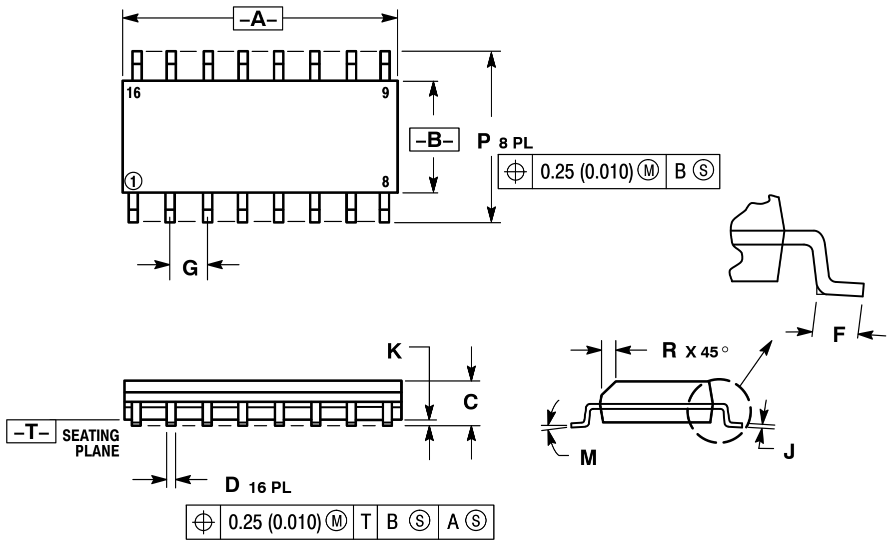
CASE 751B−05
ISSUE K

DATE 29 DEC 2006



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 1:
PIN 1. COLLECTOR
2. BASE
3. EMITTER
4. NO CONNECTION
5. EMITTER
6. BASE
7. COLLECTOR
8. COLLECTOR
9. BASE
10. EMITTER
11. NO CONNECTION
12. EMITTER
13. BASE
14. COLLECTOR
15. EMITTER
16. COLLECTOR

STYLE 2:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION
4. CATHODE
5. CATHODE
6. NO CONNECTION
7. ANODE
8. CATHODE
9. CATHODE
10. ANODE
11. NO CONNECTION
12. CATHODE
13. CATHODE
14. NO CONNECTION
15. ANODE
16. CATHODE

STYLE 3:
PIN 1. COLLECTOR, DYE #1
2. BASE, #1
3. EMITTER, #1
4. COLLECTOR, #1
5. COLLECTOR, #2
6. BASE, #2
7. EMITTER, #2
8. COLLECTOR, #2
9. COLLECTOR, #3
10. BASE, #3
11. EMITTER, #3
12. COLLECTOR, #3
13. COLLECTOR, #4
14. BASE, #4
15. EMITTER, #4
16. COLLECTOR, #4

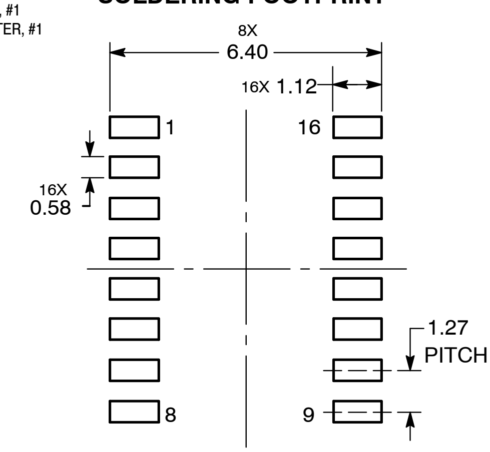
STYLE 4:
PIN 1. COLLECTOR, DYE #1
2. COLLECTOR, #1
3. COLLECTOR, #2
4. COLLECTOR, #2
5. COLLECTOR, #3
6. COLLECTOR, #3
7. COLLECTOR, #4
8. COLLECTOR, #4
9. BASE, #4
10. EMITTER, #4
11. BASE, #3
12. EMITTER, #3
13. BASE, #2
14. EMITTER, #2
15. BASE, #1
16. EMITTER, #1

STYLE 5:
PIN 1. DRAIN, DYE #1
2. DRAIN, #1
3. DRAIN, #2
4. DRAIN, #2
5. DRAIN, #3
6. DRAIN, #3
7. DRAIN, #4
8. DRAIN, #4
9. GATE, #4
10. SOURCE, #4
11. GATE, #3
12. SOURCE, #3
13. GATE, #2
14. SOURCE, #2
15. GATE, #1
16. SOURCE, #1

STYLE 6:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. CATHODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE
15. ANODE
16. ANODE

STYLE 7:
PIN 1. SOURCE N-CH
2. COMMON DRAIN (OUTPUT)
3. COMMON DRAIN (OUTPUT)
4. GATE P-CH
5. COMMON DRAIN (OUTPUT)
6. COMMON DRAIN (OUTPUT)
7. COMMON DRAIN (OUTPUT)
8. SOURCE P-CH
9. SOURCE P-CH
10. COMMON DRAIN (OUTPUT)
11. COMMON DRAIN (OUTPUT)
12. COMMON DRAIN (OUTPUT)
13. GATE N-CH
14. COMMON DRAIN (OUTPUT)
15. COMMON DRAIN (OUTPUT)
16. SOURCE N-CH

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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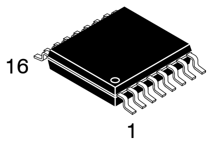
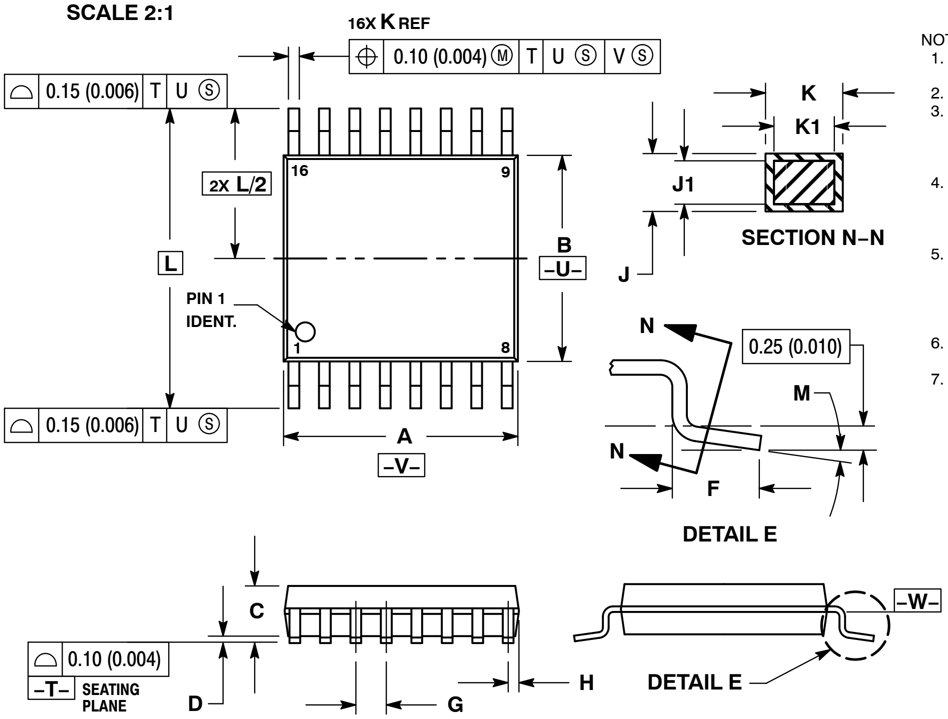
DESCRIPTION:	SOIC−16	PAGE 1 OF 1



SCALE 2:1

TSSOP−16 WB
CASE 948F
ISSUE B

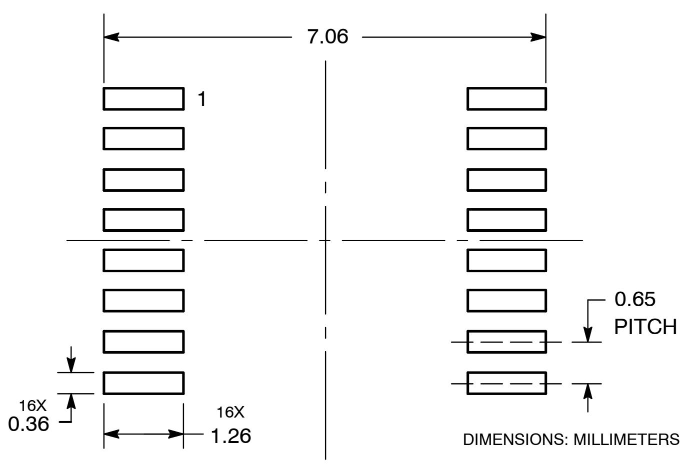
DATE 19 OCT 2006



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

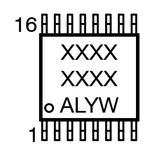
	MILLIMETERS		INCHES	
DIM	**MIN**	**MAX**	**MIN**	**MAX**
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	−−−	1.20	−−−	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
G or ▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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